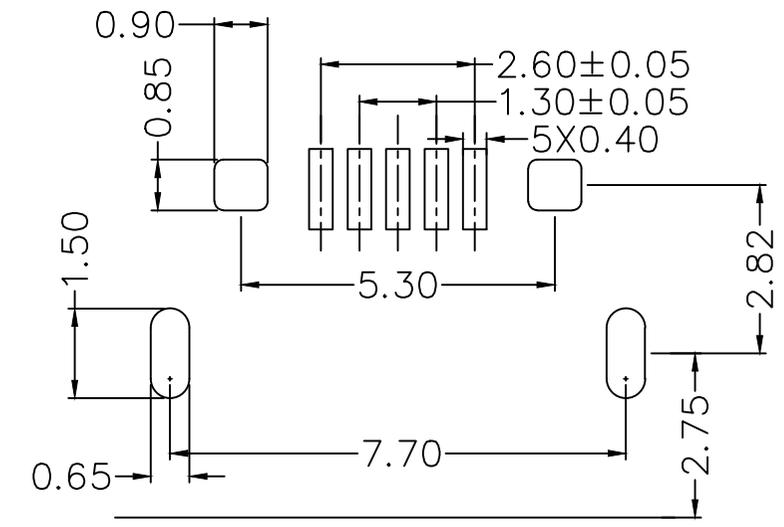
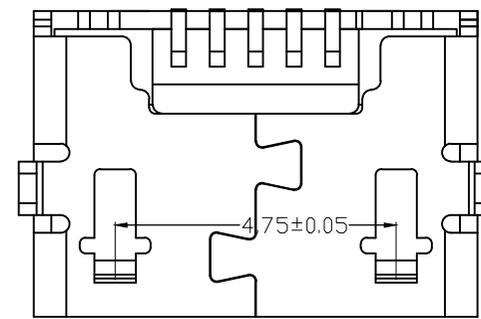
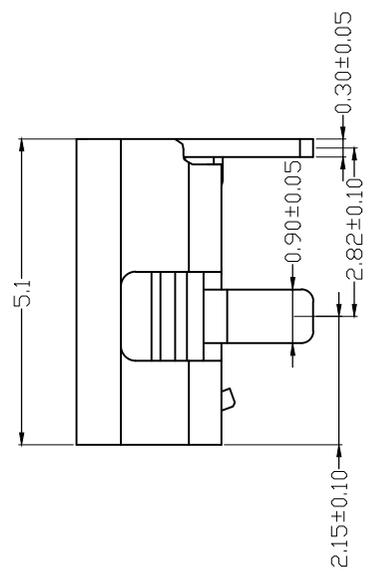
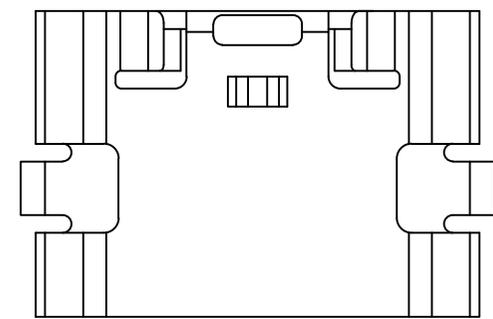
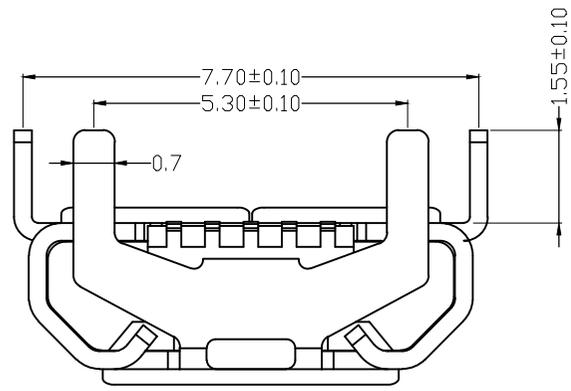
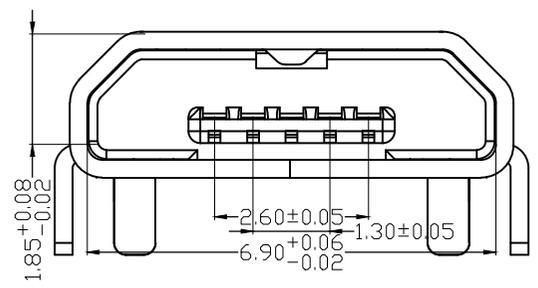


REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2011/10/31



PCB LAYOUT

- Note:
- Material:
 - Housing: High temperature thermoplastic with g.f,UL94v-0
 - Contact: copper alloy,t=0.15mm
 - Shell: copper alloy&SUS
 - Specification:
 - Current rating: 1 A Max.
 - Dielectric withstanding voltage: 100 V(ac) for 1 min.
 - Contact resistance: 30 mΩ Max.
 - Insulation resistance: 100 MΩ Min.
 - Total mating force: 3.57 Kgf Max.
 - Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.after 10000 insertion/extraction cycles
 - Temperature range: -30°C~80°C



GENERAL TOLERANCE		DWG NO.	JYSA1014-03	APPD:	WIND	Scale	1:1
X.±0.45	x.'±5'	Title	MICRO USB SPIN 反向牛角型7.7+5.3mm 平口 无柱	CHKD:		UNIT	mm
.X±0.35	.x'±2'			DR:			
.XX±0.25	.xx'±1'	Part NO.	JYS-USB770-075	Date	2011/10/31		
.XXX±0.15	.xxx'±0.5'						
SHEET	1/1			Shenzhen JYSCONN Electronics Co., LTD.			